

## General Description

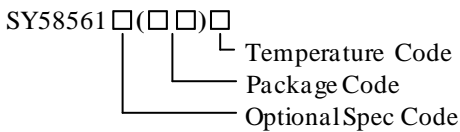
SY58561 is a single-stage Buck PFC driver for LED lighting applications. Good compatibility is achieved with Leading/Trailing edge dimmer and high PF is achieved without any dimmer.

SY58561 drives the converter in Quasi-Resonant mode to achieve high efficiency. Reliable Open/Short LED protections are integrated.

SY58561 integrates high voltage power FET inside to save driver space further.

SY58561 is available in SOT23-5 package.

## Ordering Information



Ordering Number	Package type	Note
SY58561AAC	SOT23-5	----

## Features

- Compatible with Leading edge/Trailing edge dimmer
- High PF without any dimmer
- 350V MOSFET integrated
- Quasi-Resonant operation
- Reliable Open/Short LED protection
- Thermal fold back
- Low BOM cost
- Maximum Output Power: 10W
- RoHS Compliant and Halogen Free
- Compact package: SOT23-5

## Applications

- LED lighting
- Leading edge dimming
- Trailing edge dimming

## Typical Applications

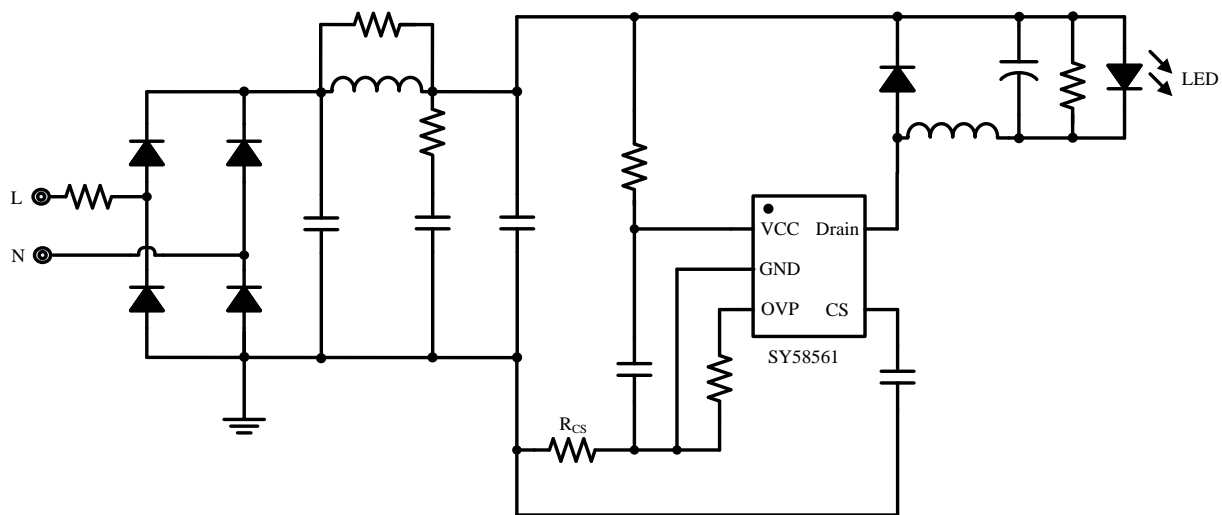
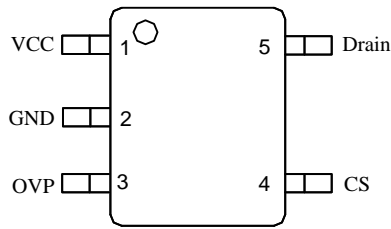


Fig.1 Typical application

**Pinout** (top view)



**(SOT23-5)**

**Top Mark: Saxyz** (device code: Sa, *x=year code, y=week code, z=lot number code*)

Pin name	Pin Number	Pin Description
VCC	1	Bias supply pin.
GND	2	Ground pin.
OVP	3	Over voltage protection set pin. Connect a resistor to GND.
CS	4	Current sense pin, connect a cap and sense res to GND pin.
Drain	5	Internal MOSFET drain node.

**Block Diagram**

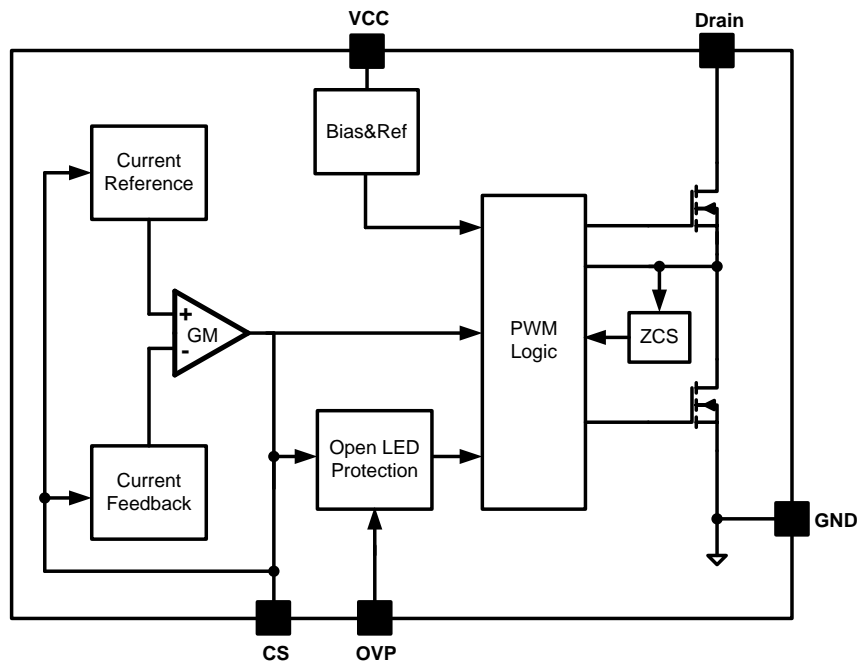


Fig.2 Simplified block diagram

## Absolute Maximum Ratings (Note 1)

VCC -----	-0.3V~20V
I <sub>VCC</sub> -----	4mA
CS, OVP -----	-0.3V~4V
Drain -----	350V
Power Dissipation, @ TA = 25°C SOT23-5 -----	0.6W
Package Thermal Resistance (Note 2)	
SOT23-5, θ <sub>JA</sub> -----	170°C/W
SOT23-5, θ <sub>JC</sub> -----	130°C/W
Maximum Junction Temperature -----	165°C
Lead Temperature (Soldering, 10 sec.) -----	260°C
Storage Temperature Range -----	-65°C to 165°C

## Recommended Operating Conditions

Junction Temperature Range -----	-40°C to 125°C
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## Electrical Characteristics

( $V_{VCC} = 12V$ ,  $T_A = 25^\circ C$  unless otherwise specified)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
<b>Power Supply Section</b>						
VCC turn-on threshold	$V_{VCC\_ON}$		13.2	14.1	15.0	V
VCC turn-off threshold	$V_{VCC\_OFF}$		6.5	7.5	8.0	V
VCC shunt voltage	$V_{VCC\_Shunt}$	$I_{VCC}=1.0mA$	13.5	14.5	15.5	V
Start up current	$I_{ST}$		38	50	60	$\mu A$
Quiescent current	$I_Q$		250	310	370	$\mu A$
<b>CS pin Section</b>						
Current reference	$V_{REF}$		500	518	536	mV
Current limit	$V_{CS\_MAX}$		1.6	1.7	1.8	V
<b>OVP pin Section</b>						
OVP Time	$T_{OVP}$			4.8		us
<b>Driver Section</b>						
Min ON Time	$t_{ON\_MIN}$			500		ns
Min OFF Time	$t_{OFF\_MIN}$			1.5		$\mu s$
Max ON Time	$t_{ON\_MAX}$			7.8		$\mu s$
Max OFF Time	$t_{OFF\_MAX}$			250		$\mu s$
<b>Integrated MOSFET Section</b>						
BV of HV MOSFET	$V_{BV}$		350			V
HV MOS Drain source resistance	$R_{DS\_ON}$			4.2	5.5	$\Omega$
<b>Thermal Section</b>						
Thermal fold back temperature	$T_{FB}$			160		$^\circ C$
Thermal shut down temperature	$T_{SD}$			$T_{FB} + 5$		$^\circ C$

**Note 1:** Stresses beyond the “Absolute Maximum Ratings” may cause permanent damage to the device. These are stress ratings only. Functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

**Note 2:**  $\theta_{JA}$  is measured in the natural convection at  $T_A = 25^\circ C$  on a low effective single layer thermal conductivity test board of JEDEC 51-3 thermal measurement standard. Test condition: Device mounted on “2 x 2” FR-4 substrate PCB, 2oz copper, with minimum recommended pad on top layer and thermal via to bottom layer ground plane.

**Note 3:** Increase VCC pin voltage gradually higher than  $V_{VCC\_ON}$  voltage then turn down to 12V.

## Operation

The SY58561 is a single stage Buck PFC regulator targeting at LED lighting applications.

It is mainly used on dimming applications and has good compatibility with Leading/Trailing edge dimmer.

In order to reduce the switching losses and improve EMI performance, Quasi-Resonant switching mode is applied, which means to turn on the power MOSFET at the valley of drain voltage.

It also provides reliable open/short LED protections and over temperature protection.

The IC is available with SOT-23 package.

## Applications Information

### Start up

After AC supply is powered on, the capacitor  $C_{VCC}$  between VCC and GND pin is charged up by BUS voltage. Once  $V_{VCC}$  rises up to  $V_{VCC\_ON}$ , the internal blocks start to work and  $V_{CS}$  is pre-charged to certain value.

The whole start up procedure is divided into three sections as shown below.  $t_{ST1}$  is the  $C_{VCC}$  charged up time.  $t_{ST2}$  is the time  $V_{CS}$  is charged up to certain value.  $t_{ST3}$  is the time IC works at steady state. Usually  $t_{ST2}$  is much smaller than  $t_{ST1}$ .

If bias supply has more power than IC consumption,  $V_{VCC}$  is greater than  $V_{VCC\_Shunt}$ , then a shunt current starts to work.

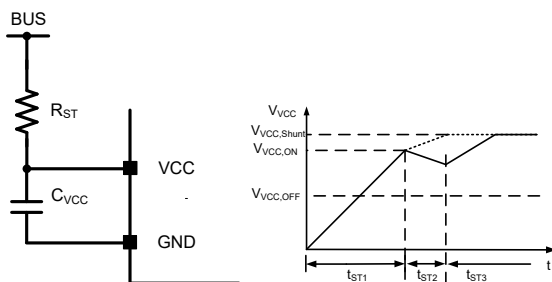


Fig.3 Start up

The start up component  $R_{ST}$  and  $C_{VCC}$  are designed as below:

(a) Preset start-up resistor  $R_{ST}$ , make sure that the current through  $R_{ST}$  is larger than  $I_{ST}$ .

$$R_{ST} < \frac{V_{BUS}}{I_{ST}}$$

For dimming applications, make sure that the current through  $R_{ST}$  is larger than  $I_Q$ . In the minimum angle of dimmer, the  $V_{BUS\_MIN}$  is equal to the LED voltage.

$$R_{ST} < \frac{V_{BUS\_MIN} - V_{VCC\_OFF}}{I_Q}$$

$$V_{BUS\_MIN} = V_{LED\_Min\_Current}$$

(b) Select  $C_{VCC}$  to obtain an ideal start up time  $t_{ST}$ , and to make sure that the  $V_{VCC} > V_{VCC\_OFF}$  in  $t_{ST2}$ .

The recommended formula is as below:

$$C_{VCC} = \frac{(\frac{V_{BUS}}{R_{ST}} - I_{ST}) \times t_{ST}}{V_{VCC\_ON}}$$

### Shut down

After AC supply is powered off, the energy stored in the BUS capacitor is discharged. When power supply for IC is not enough,  $V_{VCC}$  drops down. Once  $V_{VCC}$  is below  $V_{VCC\_OFF}$ , the IC stops working.

### LED current setting

The LED current is set by the resistor  $R_{CS}$ . The relationship is as below:

$$I_{LED} = \frac{V_{REF}}{2 \times R_{CS}}$$

### Open LED protection

The protection voltage  $V_{OVP}$  for open LED is set by the resistor  $R_{OVP}$  between OVP pin and GND pin. The relationship is shown as below:

$$R_{OVP} = \frac{L_M \times K_{OVP}}{V_{OVP} \times R_{CS} \times T_{OVP}}$$

$K_{OVP}$  is typically  $2200(V \cdot \Omega)$ . If over voltage protection is triggered, the PWM output is stopped and  $V_{VCC}$  is discharged. Once  $V_{VCC}$  drops down to  $V_{VCC\_OFF}$ , the IC stops working and then starts up again.

### Short LED protection

If LED is short, the PWM output is stopped and  $V_{VCC}$  is discharged. Once  $V_{VCC}$  drops down to  $V_{VCC\_OFF}$ , the IC stops working and then starts up again.

## Thermal treatment

Thermal fold back is adopted in this IC. Thermal fold back curve is shown as below.

When the junction temperature rises high, internal current reference decreases first; if the junction temperature still rises up over  $T_{SD}$ , IC will be shut down.

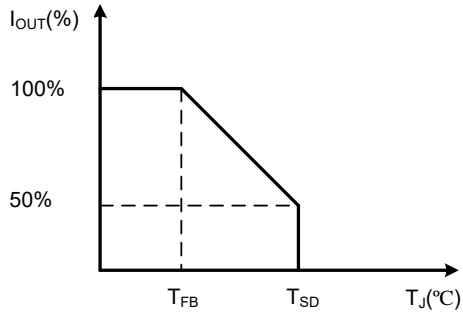


Fig.4 Thermal foldback curve

## Power Device Design

### MOSFET and Diode

When the operation condition is with maximum input voltage, the voltage stress of MOSFET and output power diode is maximized. MOSFET is integrated with 350V BV.

$$V_{DS\_MAX} = \sqrt{2}V_{AC\_MAX}$$

Where  $V_{AC\_MAX}$  is maximum input AC RMS voltage.

### Inductor (L)

In Buck converter, the power transfers from AC input to output only when the input voltage is larger than the output voltage. The input voltage and inductor current waveforms are shown below, where  $\theta_3$  and  $\theta_4$  are the time that input voltage is equal to output voltage.

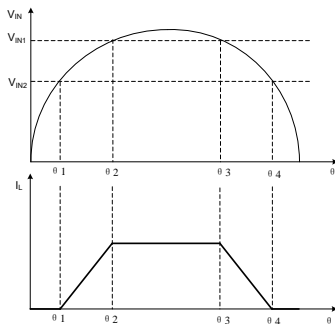


Fig.5 Input and output waveforms

The system operates in the peak current mode. The ON time increases with the input voltage decreasing. When the ON time reaches  $T_{ON\_MAX}$ , the ON time is limit by  $T_{ON\_MAX}$ . Where  $\theta_1$  and  $\theta_2$  are the time that ON time is equal to  $T_{ON\_MAX}$ .

In Quasi-Resonant mode, each switching period  $t_s$  consists of three parts: inductor current rising time  $t_1$ , falling time  $t_2$  and quasi-resonant time  $t_3$ .

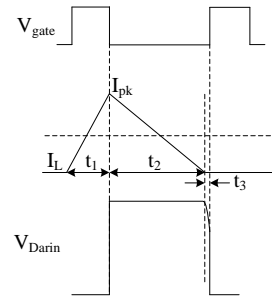


Fig.6 switching waveforms

The switching frequency is designed in rated input voltage considering conducted EMI test. Once the switching frequency  $f_{sw}$  is set, the inductance of the inductor could be calculated.

The design flow is shown as below:

(a) Preset frequency  $f_{sw}$

(b) Compute relative  $t_s, t_1$

$$t_s = \frac{1}{f_{sw}}$$

$$t_1 = \frac{t_s \times (V_{OUT} + V_{DF})}{(\sqrt{2}V_{AC\_MIN} + V_{DF})}$$

$$t_2 = t_s - t_1$$

Where  $V_{DF}$  is the forward voltage of diode,  $V_{AC\_MIN}$  is the RMS value of minimum input voltage.

(c) Compute the peak current of inductance  $I_{PK}$ .

$$\theta_1 = \arcsin\left(\frac{V_{OUT}}{\sqrt{2}V_{AC\_MIN}}\right)$$

$$\theta_2 = \arcsin\left(\frac{\frac{\sqrt{2}V_{AC\_MIN} - V_{OUT}}{t_{ON\_MAX}} \times t_1 + V_{OUT}}{\sqrt{2}V_{AC\_MIN}}\right)$$

$$I_{PK} = \frac{2 \times I_{OUT}}{1 - \frac{\theta_1}{\pi} - \frac{\theta_2}{\pi}}$$

Where  $V_{OUT}$  is the rated output voltage,  $I_{OUT}$  is rated output current.

(d) Design inductance L

$$L = \frac{(\sqrt{2}V_{AC\_RMS\_R} - V_{OUT}) \times t_1}{I_{PK}}$$

### Inductor design (N)

Necessary parameters:	
Inductance	L
Io program resistor	$R_{CS}$
Current limit voltage	$V_{REF}$

The design rules are as followed:

(a) Select the magnetic core style, identify the effective area  $A_e$ .

(b) Preset the maximum magnetic flux  $\Delta B$ .  
For PC40,  $\Delta B$  select 0.3~0.33T at 25° C.

(c) Compute inductor maximum peak current  $I_{L\_PK\_MAX}$  and maximum RMS current  $I_{L\_RMS\_MAX}$ .

$$I_{L\_PK\_MAX} = \frac{V_{CS\_MAX} - V_{REF}}{R_{CS}}$$

$$I_{L\_RMS\_MAX} = \frac{1}{\sqrt{3}} I_{L\_PK\_MAX}$$

(d) Compute turn N

$$N = \frac{L}{\Delta B \times A_e} \times I_{L\_PK\_MAX}$$

(e) Select an appropriate wire diameter with  $I_{L\_RMS\_MAX}$ , select appropriate wire to make sure the current density ranges from 4A/mm<sup>2</sup> to 10A/mm<sup>2</sup>.

(f) If the winding area of the core and bobbin is not enough, reselect the core style, go to (a) and redesign the inductor until the ideal inductor is achieved.

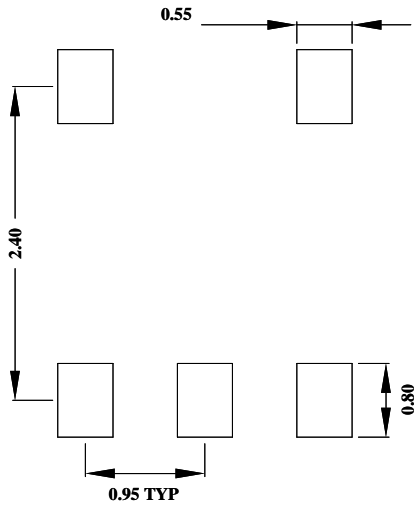
### Output capacitor $C_{OUT}$

Choose proper output capacitance to satisfy current ripple. Output current ripple is set to  $\Delta I_O$ , then,

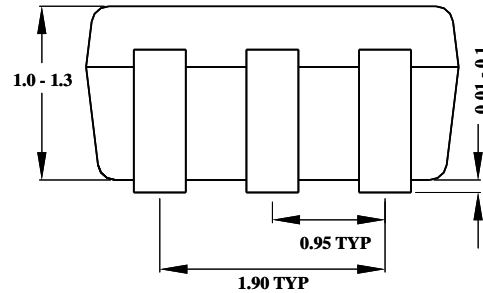
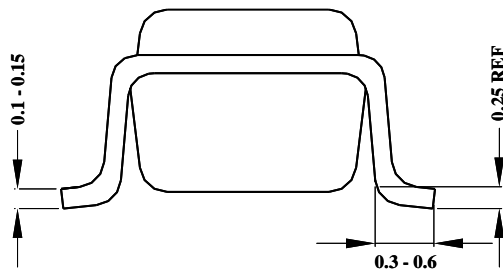
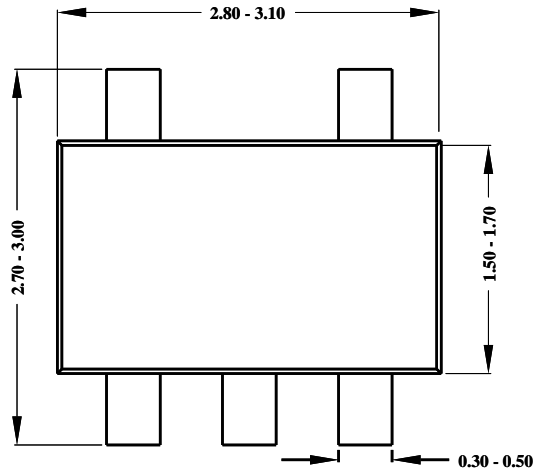
$$C_{OUT} = \frac{\sqrt{\left(\frac{2I_{OUT}}{\Delta I_O}\right)^2 - 1}}{4\pi \times R_{LED} \times f_{AC}}$$

Where  $f_{AC}$  is the AC supply frequency;  $R_{LED}$  is the equivalent series resistor of LED load.

**SOT23-5 Package outline & PCB layout design**



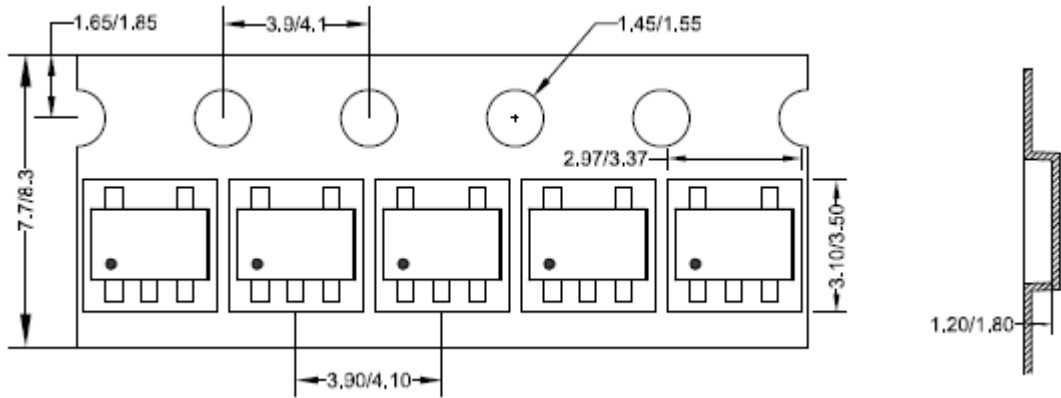
**Recommended Pad Layout**



**Notes: All dimensions are in millimeters.  
All dimensions don't include mold flash & metal burr.**

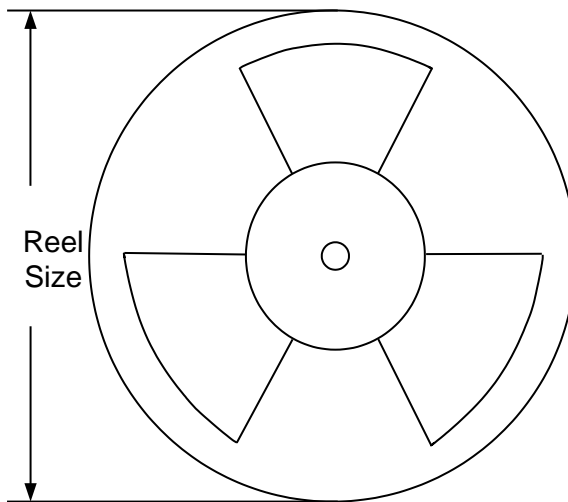
## Taping & Reel Specification

### 1. Taping orientation for packages (SOT23-5)



Feeding direction →

### 2. Carrier Tape & Reel specification for packages



Package type	Tape width (mm)	Pocket pitch(mm)	Reel size (Inch)	Trailer length(mm)	Leader length (mm)	Qty per reel
SOT23-5	8	4	7"	280	160	3000

## Revision History

The revision history provided is for informational purpose only and is believed to be accurate, however, not warranted. Please make sure that you have the latest revision.

<b>Date</b>	<b>Revision</b>	<b>Change</b>
October 20,2018	Revision 0.9	Initial Risk Production Release
October 20,2019	Revision 1.0	Initial Production Release

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